Unit: mm

2.9±0.2

4.6±0.2

φ3<mark>.2±</mark>0.1

15.0±0.3

2SC5037, 2SC5037A

Silicon NPN triple diffusion planar type

For high breakdown voltage high-speed switching

Features

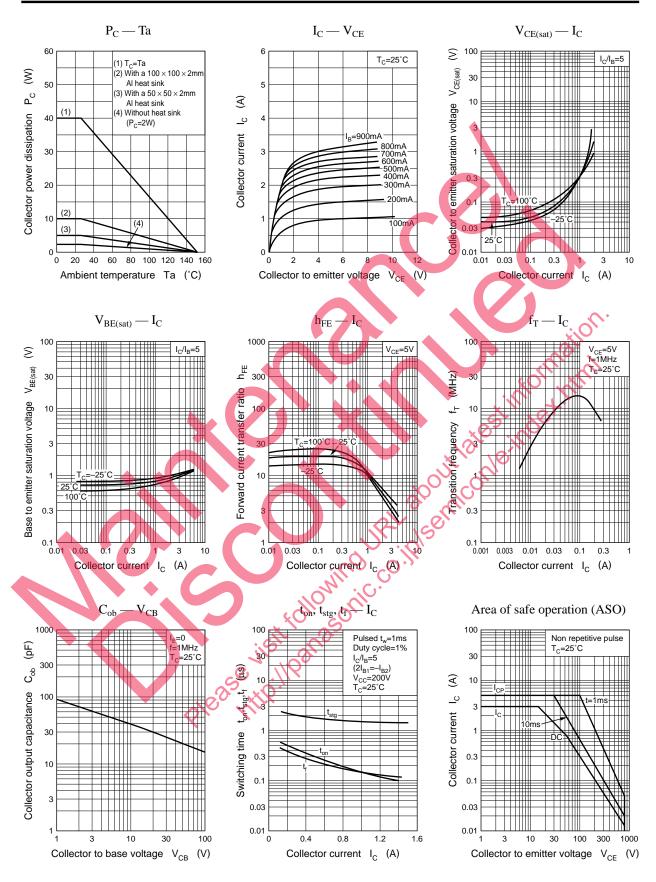
- High-speed switching ٠
- High collector to base voltage V_{CBO} •
- Wide area of safe operation (ASO)
- Satisfactory linearity of foward current transfer ratio h_{FF} •
- Full-pack package with outstanding insulation, which can be in-• stalled to the heat sink with one screw

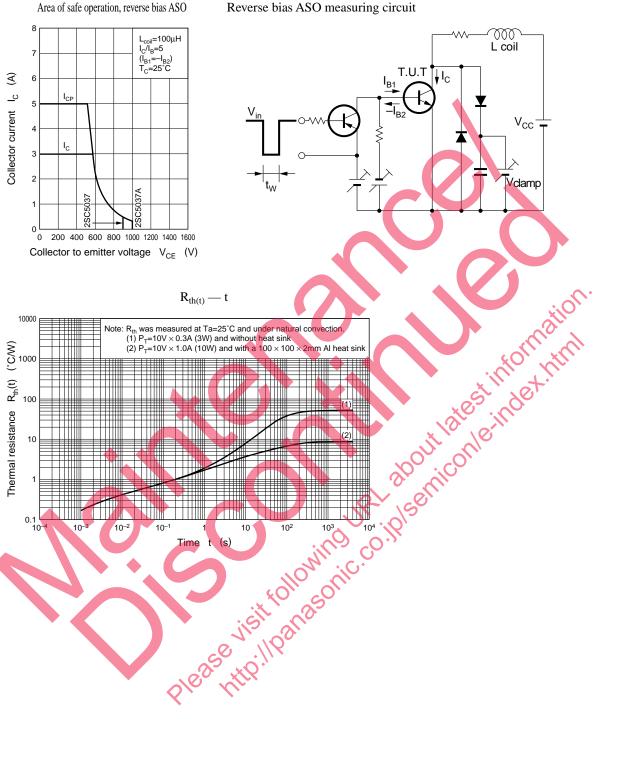


Electrical Characteristics (T_c=25°C)

Parameter		Symbol	Conditions	min	typ	max	Unit
Collector cutoff	2SC5037	LEBO X	$V_{CB} = 900V, I_E = 0$			50	
current	2SC5037A	10BO	$V_{CB} = 1000 V, I_E = 0$			50	μΑ
Emitter cutoff current		I _{EBO}	$V_{EB} = 7V, I_C = 0$			50	μA
Collector to emitter voltage		V _{CEO}	$I_{\rm C} = 10 {\rm mA}, I_{\rm B} = 0$	800			μA
Forward current transfer ratio		h _{FE1}	$V_{CE} = 5V, I_C = 0.1A$	8			v
		h _{FE2}	$V_{CE} = 5V, I_C = 0.8A$	6			
Collector to emitter saturation voltage		V _{CE(sat)}	$I_{\rm C} = 0.8$ A, $I_{\rm B} = 0.16$ A			1.5	v
Base to emitter saturation voltage		V _{BE(sat)}	$I_{\rm C} = 0.8 A, I_{\rm B} = 0.16 A$			1.5	v
Transition frequency		f _T	$V_{CE} = 5V, I_C = 0.15A, f = 1MHz$		10		MHz
Turn-on time		t _{on}	$I_{C} = 0.8A, I_{B1} = 0.16A, I_{B2} = -0.32A,$ $V_{CC} = 250V$			0.7	μs
Storage time		t _{stg}				2.5	μs
Fall time		t _f				0.3	μs

Panasonic





Reverse bias ASO measuring circuit

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